

Title (en)
Thermoplastic resin composition

Title (de)
Thermoplastische Harzzusammensetzung

Title (fr)
Composition de résine thermoplastique

Publication
EP 1170335 A3 20030205 (EN)

Application
EP 01116233 A 20010704

Priority
JP 2000204512 A 20000706

Abstract (en)
[origin: EP1170335A2] The invention provides a thermoplastic resin composition high in mechanical strength such as flexural strength, weld strength and tensile elongation and excellent in moldability and friction property. The resin composition contains a polyamide resin component composed of 5 to 95% by weight of the following component (A) and 95 to 5% by weight of the following component (B) : Component (A): a polyamide resin obtained by polycondensing diamine(s) including at least tetramethylenediamine with dicarboxylic acid(s) including at least adipic acid; and Component (B): a polyamide resin obtained by polycondensing diamine(s) including at least one of 1,9-nonanediamine and 2-methyl-1,8-octanediamine with dicarboxylic acid(s) including at least terephthalic acid.

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C08L 77/00; **C08L 77/06**; **C08G 69/26**

IPC 8 full level
C08G 69/26 (2006.01); **C08K 3/00** (2006.01); **C08L 77/00** (2006.01); **C08L 77/06** (2006.01); **H01L 23/29** (2006.01); **H01L 23/31** (2006.01)

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Citation (search report)

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